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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TAGUCHI ET AL

Application No.: 09/642,765

Art Unit: 1725

Filed: August 22, 2000

Examiner: C. Cooke

For: LEAD-FREE SOLDER PASTE  
FOR REFLOW SOLDERING

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SEP 20 2002  
TC 1700 MAIL ROOM

SUPPLEMENTAL AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Further to the Response filed on September 10, 2002, the Applicants request that the application be amended as shown below.

IN THE CLAIMS:

Please add the following claims:

C/ 19. (New) A method as claimed in claim 16 including completely melting the plurality of metal powders in the reflow soldering.

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